

Description

Features

- V_{DS}=-30V, I_D=-10A
 - $R_{DS(ON)}$ <23m Ω @ V_{GS} = -10V
 - $R_{DS(ON)}$ < 34m Ω @ V_{GS} = -4.5V
- Advanced Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- Lead free product is acquired

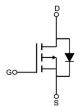
Application

- PWM Applications
- Load Switch
- Power Management

100% UIS 100% ΔVds







Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
VSM10P03-S8	VSM10P03	TAPING	SOP-8	13inch	4000	48000

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		-30	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Continuous Drain Current	T _C = 25 °C	-10	Α
		T _C = 100 ℃	-7	Α
I _{DM}	Pulsed Drain Current note1		-40	Α
P _D	Power Dissipation	T _A = 25℃	3.7	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		33.8	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	$^{\circ}$



Electrical Characteristics (TJ=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units			
Off Characteristic									
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D = -250µA	-30	-	-	V			
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30V, V_{GS} = 0V,$	-	-	-1	μA			
I _{GSS}	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA			
On Charac	On Characteristics								
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1.0	-1.5	-2.4	V			
В	Static Drain-Source on-Resistance	V _{GS} =-10V, I _D =-10A	-	16	23	mO.			
R _{DS(on)}	note2	V _{GS} =-4.5V, I _D =-5A	-	25	34	mΩ			
Dynamic C	Characteristics								
C _{iss}	Input Capacitance	\\ - 45\\\\ - 0\\	-	1550	-	pF			
Coss	Output Capacitance	$V_{DS} = -15V, V_{GS} = 0V,$	-	327	-	pF			
C _{rss}	Reverse Transfer Capacitance	f = 1.0MHz	-	278	-	pF			
Qg	Total Gate Charge	V _{DS} = -15V, I _D = -9.1A,	-	30	-	nC			
Qgs	Gate-Source Charge	$V_{DS} = -15V$, $I_D = -9.1A$, $V_{GS} = -10V$	-	5.3	-	nC			
Q_{gd}	Gate-Drain("Miller") Charge	VGS 10 V	-	7.6	-	nC			
Switching	Switching Characteristics								
t _{d(on)}	Turn-on Delay Time		-	14	-	ns			
t _r	Turn-on Rise Time	$V_{DD} = -15V$, $I_D = -6A$,	-	20	-	ns			
t _{d(off)}	Turn-off Delay Time	V_{GS} =-10V, R_{GEN} =2.5 Ω	-	95	-	ns			
t _f	Turn-off Fall Time		-	65	-	ns			
Drain-Soul	rce Diode Characteristics and Maxim	um Ratings							
Is	Maximum Continuous Drain to Source Diode Forward Current			-	-10	Α			
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	-40	Α			
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -10A	-	-0.8	-1.2	V			

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



Typical Performance Characteristics

Figure1: Output Characteristics

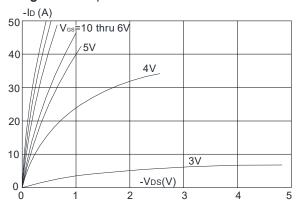


Figure 3:On-resistance vs. Drain Current

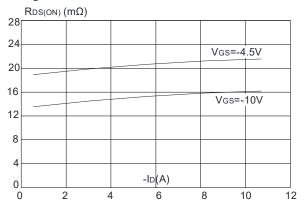


Figure 5: Gate Charge Characteristics

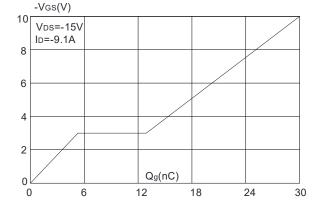


Figure 2: Typical Transfer Characteristics

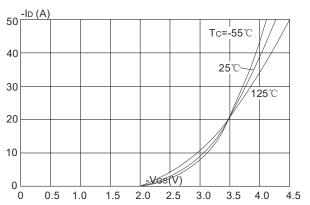


Figure 4: Body Diode Characteristics

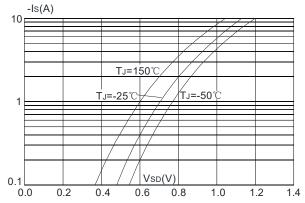


Figure 6: Capacitance Characteristics

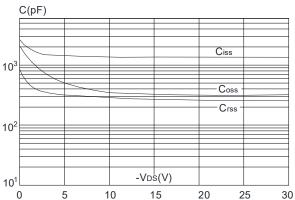




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

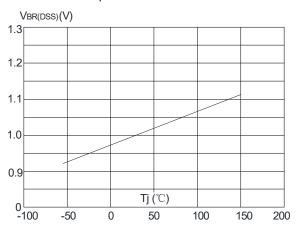


Figure 9: Maximum Safe Operating Area

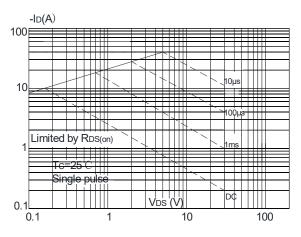


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

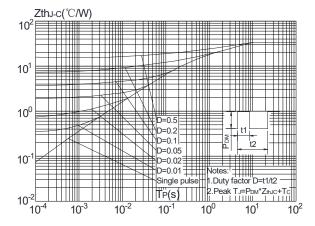


Figure 8: Normalized on Resistance vs. Junction Temperature

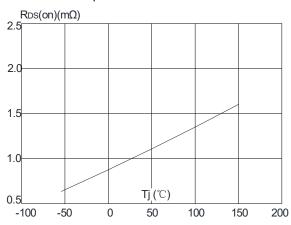
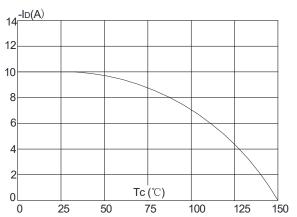
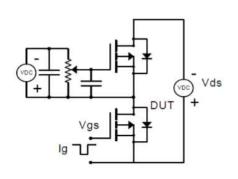


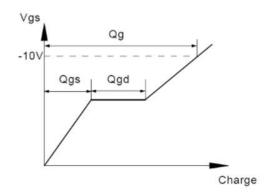
Figure 10: Maximum Continuous Drain Current vs. Case Temperature



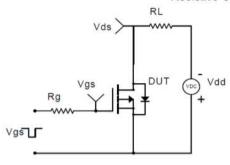


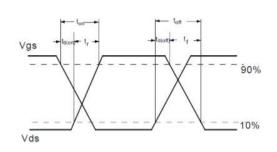
Gate Charge Test Circuit & Waveform



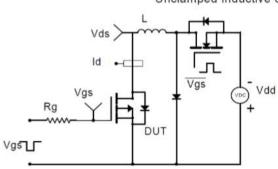


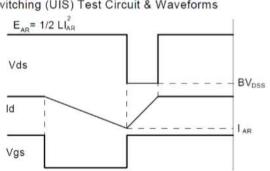
Resistive Switching Test Circuit & Waveforms





Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





Diode Recovery Test Circuit & Waveforms

